

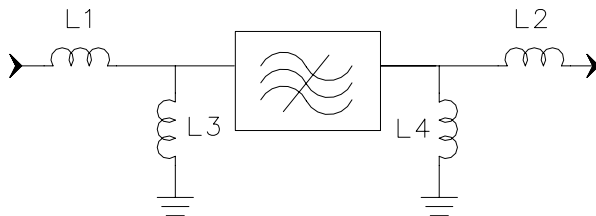
### Specifications

Parameter	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	139.8	140	140.2
Insertion Loss	dB	-	11.1	13
1 dB Bandwidth	MHz	4.5	5.1	-
3 dB Bandwidth	MHz	5	5.98	-
35 dB Bandwidth	MHz	-	8.9	9.2
Passband Variation	dB	-	0.4	1
Group delay Variation(80% of 3dB)	nsec	-	70	100
Ultimate Rejection	dB	40	45	-
Absolute Delay	usec	-	0.869	-
Substrate Material		112LT		
Ambient Temperature	°C	25		
Package Size		SF-26		

#### Notes:

1. All specifications are based on the test circuit shown
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. This is the optimum impedance in order to achieve the performance show

### Matching Configuration




**L1=22nH L2=150nH**

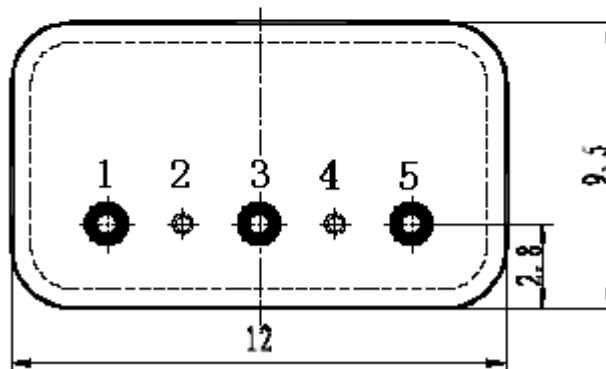
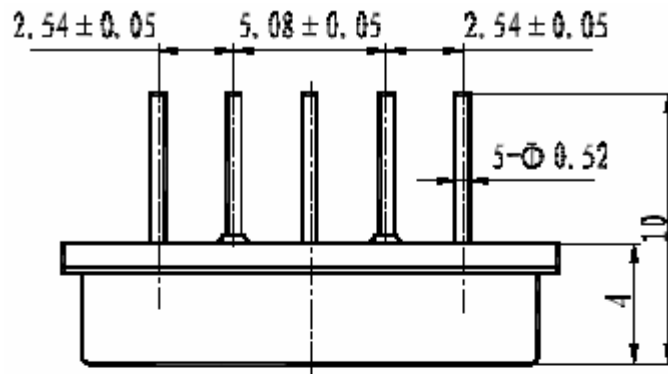
**L3=220nH L4=150nH**

**Source/Load Impedance=50 ohm**

Notes - Component values may change depending on board layout.

	<b>SIPAT Co., Ltd.</b> ( CETC No. 26 Research Institute ) Nanping Huayuan Road No. 14 Chongqing, China, 400060	Part Number	LB140DS23	
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*Package Dimension*



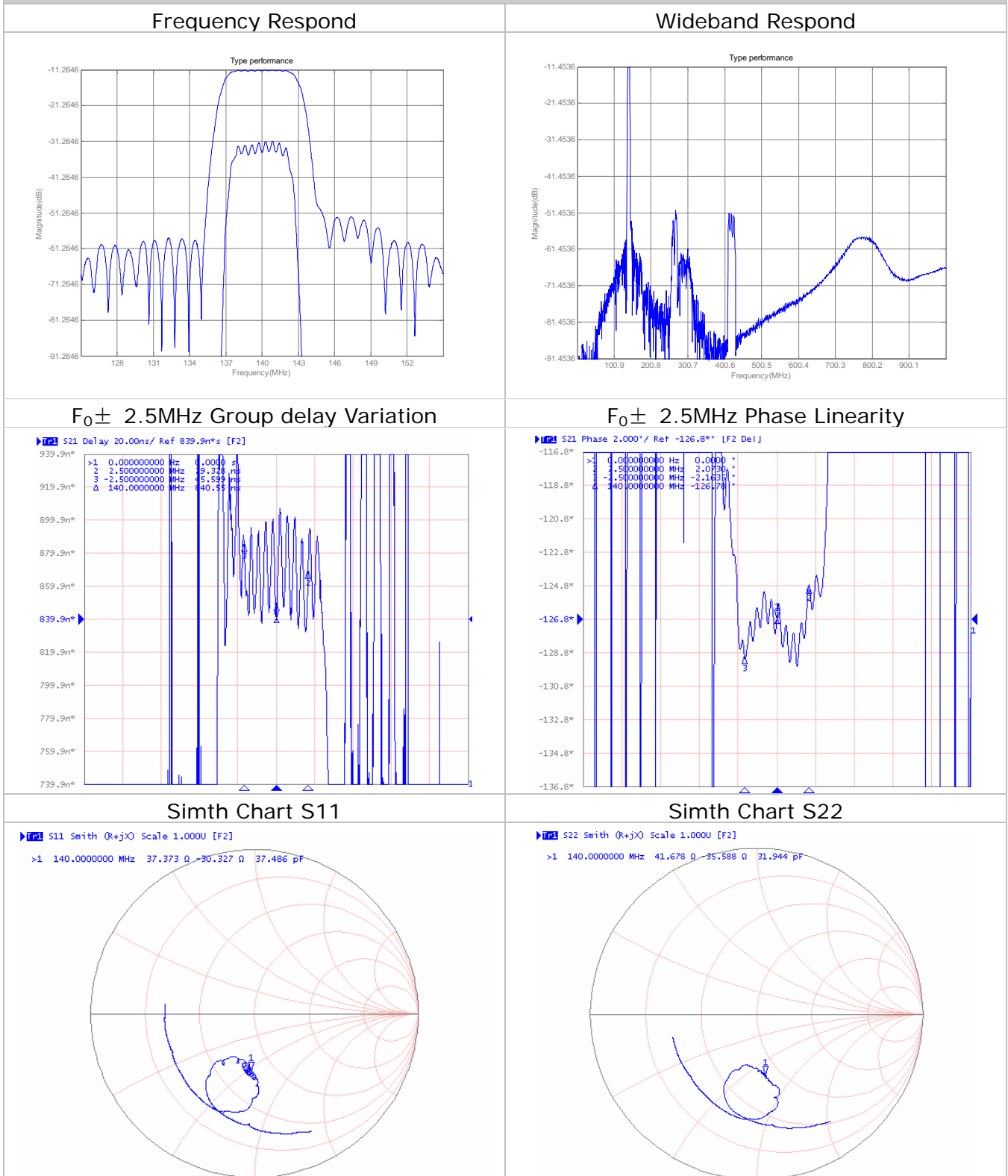
Pin 1:input  
pin 5:Output



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*Typical Performance*



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